

SPECIFICATION NO.	REV.
PSC-9000	01

Table 1: Recommended Reflow Profile

Profile Feature	Sn-Pb Assembly	Pb-free Assembly
Avg. ramp-up rate (T_L to T_P)	3°C/sec max	3°C/sec max
Preheat/Soak Min. Temp (T_{Smin}) Max. Temp (T_{Smax}) Time (ts) from (T_{Smin} to T_{Smax})	100°C 150°C 60-120 seconds	150°C 200°C 60-120 seconds
Time Maintained Above Temp(T_L) Time (t_L)	183°C 60-150 seconds	217°C 60-150 seconds
Peak Package Body Temperature (T_P)	For users, T_P must not exceed the Classification temp in Table 2. For suppliers, T_P must equal or exceed the Classification temp in Table 2.	For users, T_P must not exceed the Classification temp in Table 3. For suppliers, T_P must equal or exceed the Classification temp in Table 3.
Time within 5°C of actual Peak Temp (T_P)	20* seconds	30* seconds
Ramp-down Rate (T_P to T_L)	6°C/sec max	6°C/sec max
Time Peak Temp to 25°C	6 min max	8 min max
* Tolerance for peak profile temperature (T_P) is defined as a supplier minimum and a user maximum.		

Table 2: Sn Pb Eutectic Process – Classification Temperatures (T_C)

Package Thickness	Volume mm ² <350	Volume mm ² ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

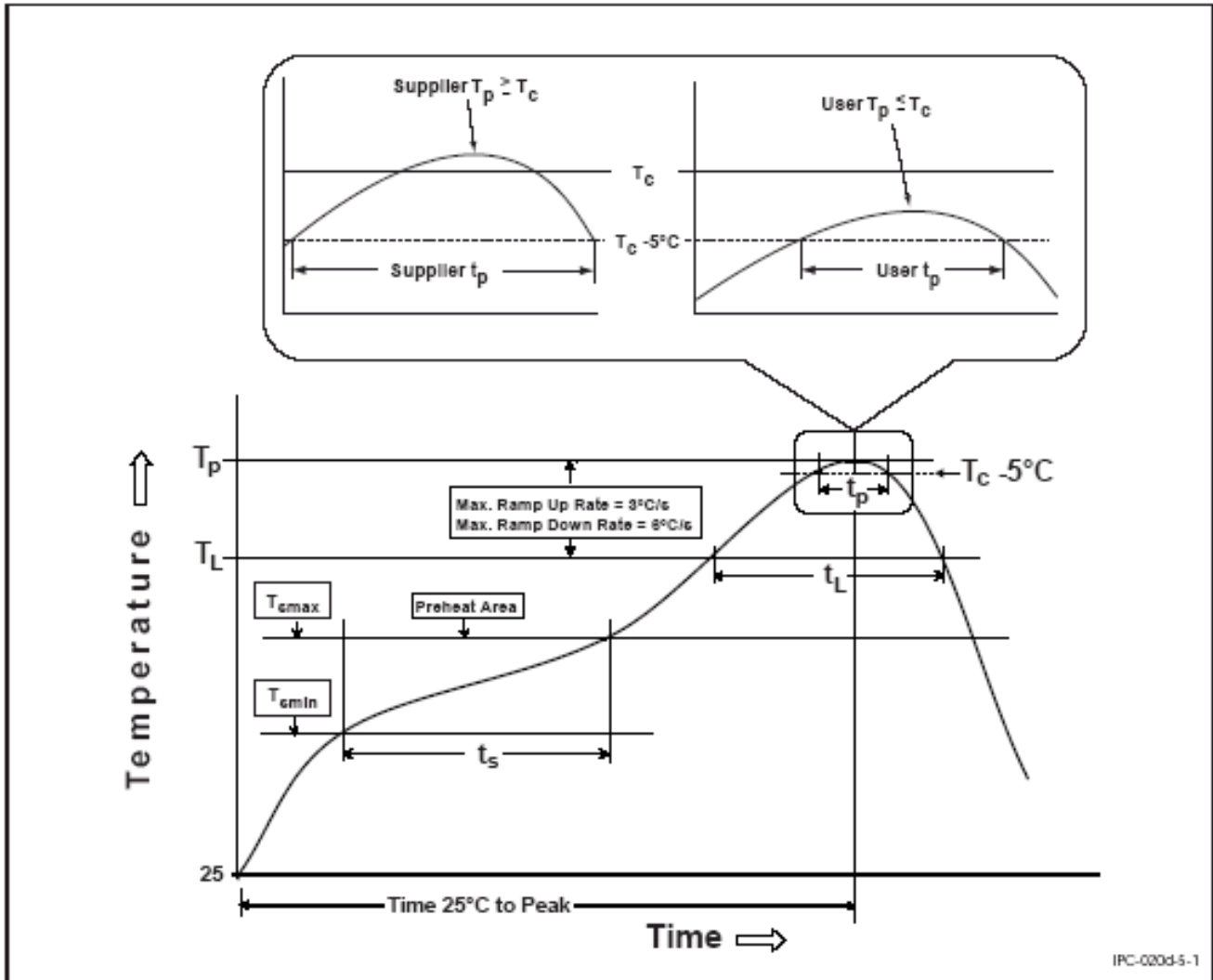
Table 3: Pb-Free Process – Classification Temperatures (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm - 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

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Reflow Profile Chart



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TITLE: Recommended Reflow Profile**REVISION HISTORY:****PRIOR REVISIONS FILED IN DOCUMENT CONTROL****REV. 01 DATE:**02/26/21**AUTHOR:** Romeo Curilan

Update the preheat/soak time for PG-free Assembly from 60-180 to 60-120 seconds

(TYPED BY AUTHOR)